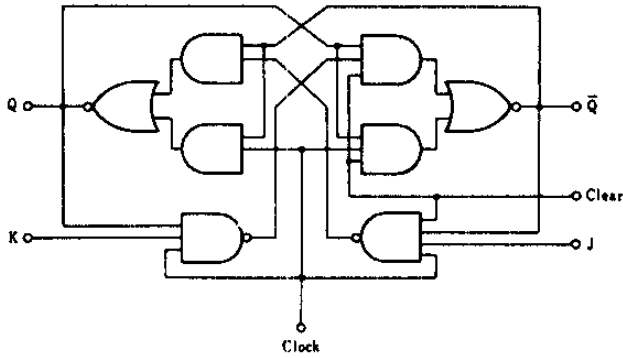
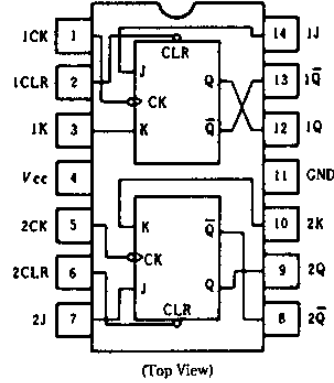


HD74LS73A ● Dual J-K Flip-Flops (with Clear)

■ BLOCK DIAGRAM (1/2)



■ PIN ARRANGEMENT



■ FUNCTION TABLE

Inputs				Outputs	
Clear	Clock	J	K	Q	\bar{Q}
L	X	X	X	L	H
H	↓	L	L	Q_0	\bar{Q}_0
H	↓	H	L	H	L
H	↓	L	H	L	H
H	↓	H	H	Toggle	
H	H	X	X	Q_0	\bar{Q}_0

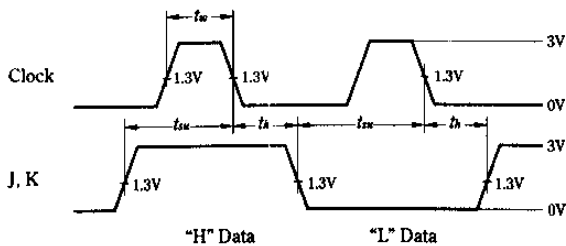
Notes) H; high level, L; low level, X; irrelevant
 ↓; transition from high to low level
 Q_0 ; level of Q before the indicated steady-state input conditions were established.
 \bar{Q}_0 ; complement of Q_0 or level of Q before the indicated steady-state input conditions were established.
 Toggle; each output changes to the complement of its previous level on each active transition indicated by ↓.

■ RECOMMENDED OPERATING CONDITION

Item	Symbol	min	typ	max	Unit
Clock frequency	f_{clock}	0	—	30	MHz
Pulse width	Clock High	20	—	—	ns
	Clear Low	25	—	—	
Setup time	"H" Data	20↓	—	—	ns
	"L" Data	20↓	—	—	
Hold time	t_h	0↓	—	—	ns

Note) ↓; The arrow indicates the falling edge.

■ TIMING DEFINITION



HD74LS73A

ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ*	max	Unit	
Input voltage	V_{IH}		2.0	—	—	V	
	V_{IL}		—	—	0.8	V	
Output voltage	V_{OH}	$V_{CC}=4.75\text{V}, V_{IH}=2\text{V}, V_{IL}=0.8\text{V}, I_{OH}=-400\mu\text{A}$	2.7	—	—	V	
	V_{OL}	$V_{CC}=4.75\text{V}, V_{IH}=2\text{V}$	—	—	0.5	V	
		$V_{IL}=0.8\text{V}$	—	—	0.4	V	
Input current	J, K	I_{IH}	$V_{CC}=5.25\text{V}, V_I=2.7\text{V}$	—	—	20	μA
	Clear			—	—	60	
	Clock			—	—	80	
	J, K	I_{IL}	$V_{CC}=5.25\text{V}, V_I=0.4\text{V}$	—	—	-0.4	mA
	Clear			—	—	0.8	
	Clock			—	—	-0.8	
J, K	I_I	$V_{CC}=5.25\text{V}, V_I=7\text{V}$	—	—	0.1	mA	
Clear			—	—	0.3		
Clock			—	—	0.4		
Short-circuit output current	I_{OS}	$V_{CC}=5.25\text{V}$	-20	—	-100	mA	
Supply current **	I_{CC}	$V_{CC}=5.25\text{V}$	—	4	6	mA	
Input clamp voltage	V_{IK}	$V_{CC}=4.75\text{V}, I_{IN}=-18\text{mA}$	—	—	-1.5	V	

* $V_{CC}=5\text{V}, T_a=25^\circ\text{C}$

** With all outputs open, I_{CC} is measured with the Q and \bar{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

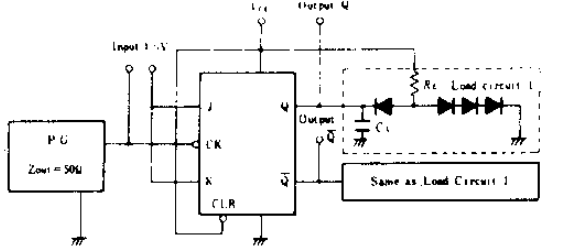
SWITCHING CHARACTERISTICS ($V_{CC}=5\text{V}, T_a=25^\circ\text{C}$)

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum clock frequency	f_{max}			$C_L = 15\text{pF}, R_L = 2\text{k}\Omega$	30	45	—	MHz
Propagation delay time	t_{PLH}	Clear	Q, \bar{Q}		—	15	20	ns
	t_{PHL}	Clock	Q, \bar{Q}	—	15	20	ns	

TESTING METHOD

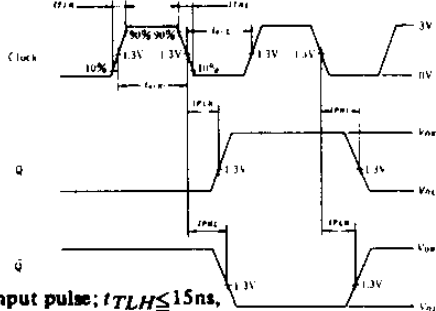
1) Test Circuit

1.1) $f_{max}, t_{PLH}, t_{PHL}$ (Clock \rightarrow Q, \bar{Q})



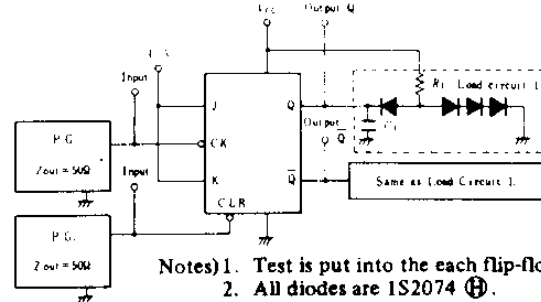
- Notes) 1. Test is put into the each flip flop
- 2. All diodes are 1S2074 \oplus .
- 3. C_L includes probe and jig capacitance.

Waveform



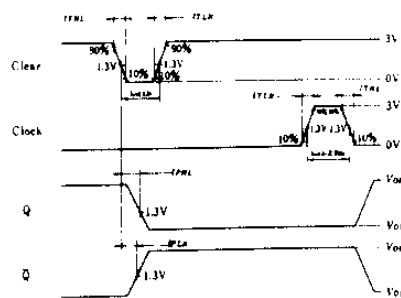
Note) Clock input pulse; $t_{TLH} \leq 15\text{ns}$,
 $t_{THL} \leq 6\text{ns}$, $PRR=1\text{MHz}$, duty
 cycle=50% and; for f_{max} ,
 $t_{TLH}=t_{THL} \leq 2.5\text{ns}$.

1.2) t_{PHL} (Clear \rightarrow Q), t_{PLH} (Clear \rightarrow \bar{Q})



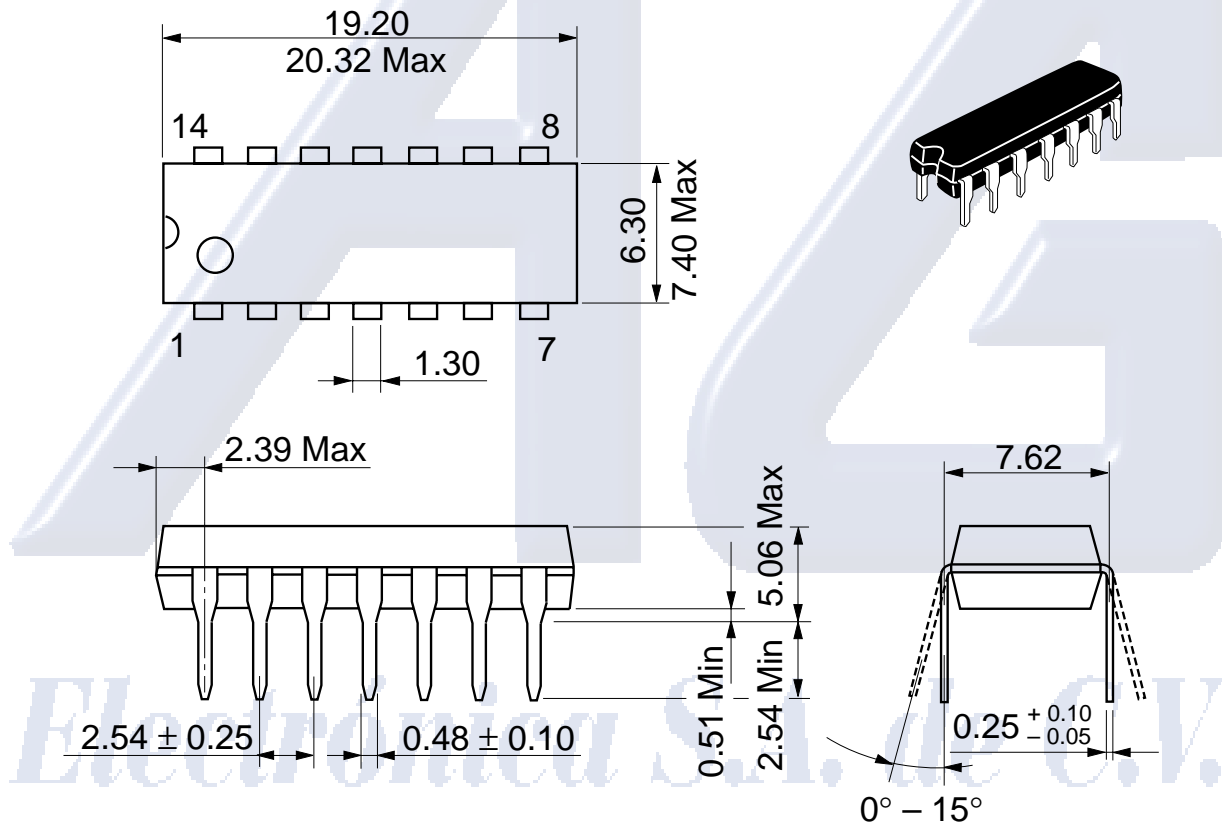
- Notes) 1. Test is put into the each flip-flop
- 2. All diodes are 1S2074 \oplus .
- 3. C_L includes probe and jig capacitance.

Waveform



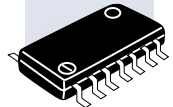
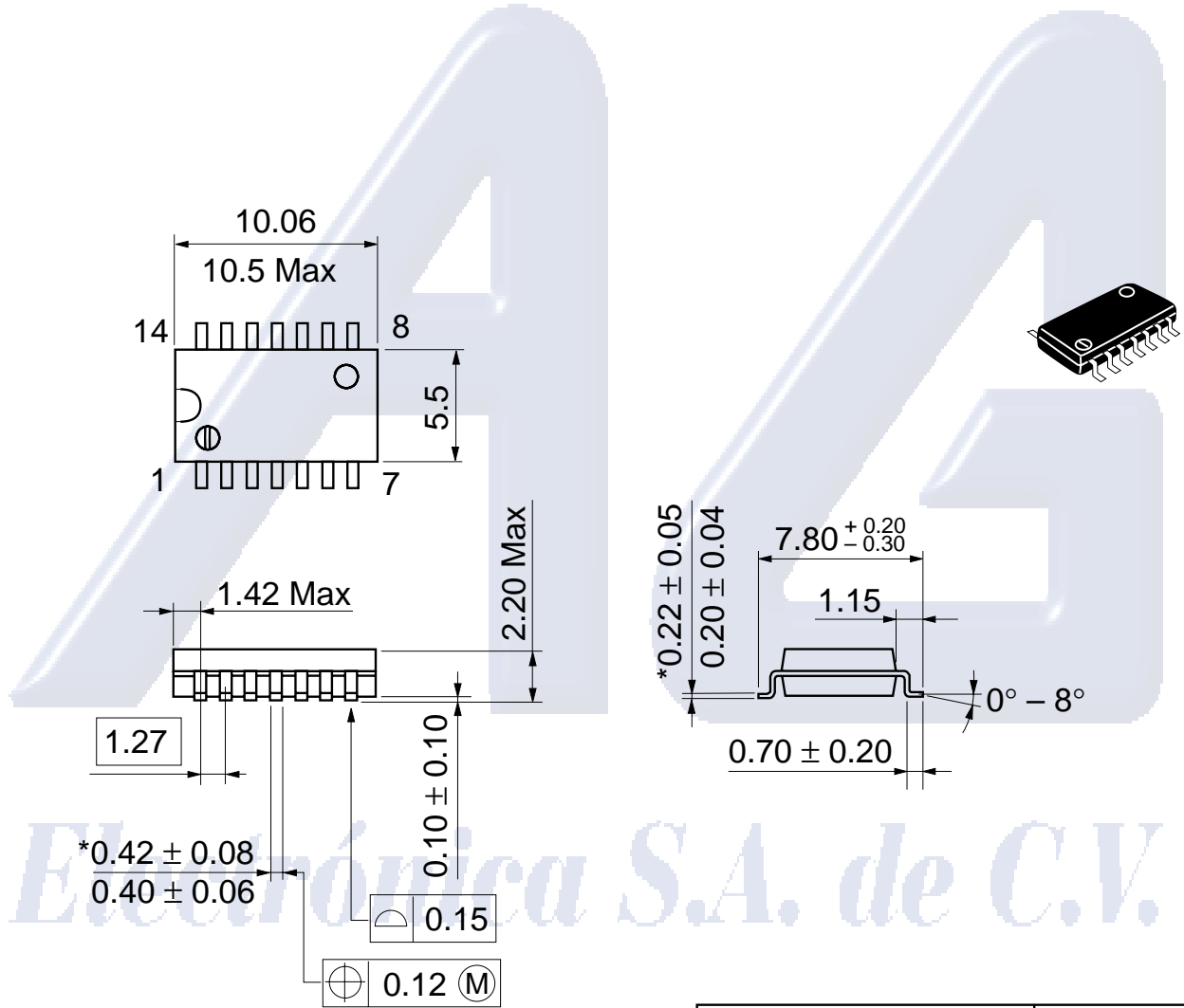
Note) Clear and clock input pulse;
 $t_{TLH} \leq 15\text{ns}$, $t_{THL} \leq 6\text{ns}$,
 $PRR=1\text{MHz}$

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

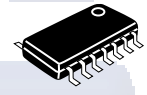
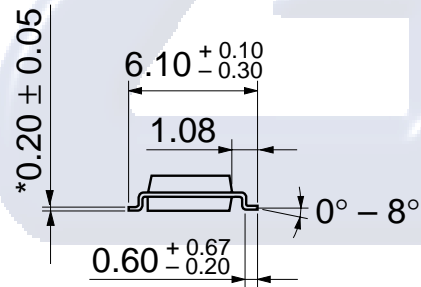
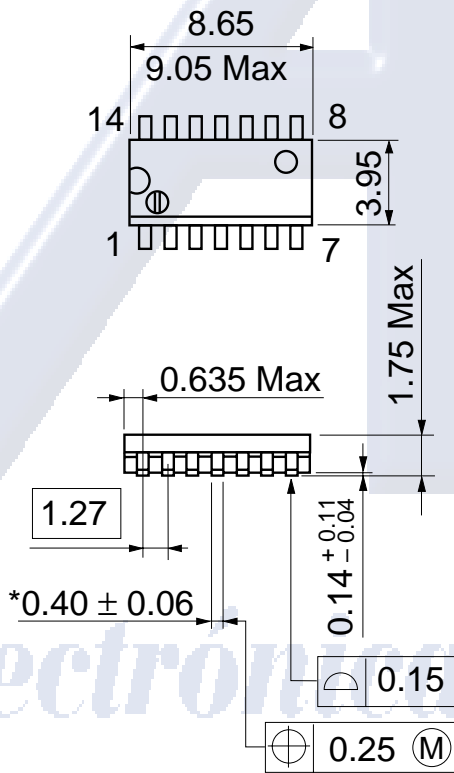


Electrónica S.A. de C.V.

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



Electronica S.A. de C.V.

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

*Pd plating

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